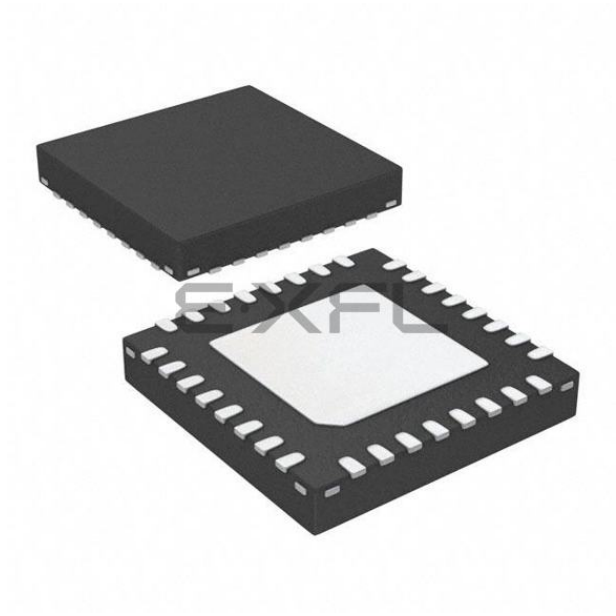

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	28
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VQFN Exposed Pad
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc11e36fhn33-501e

4.1 Ordering options

Table 2. Ordering options

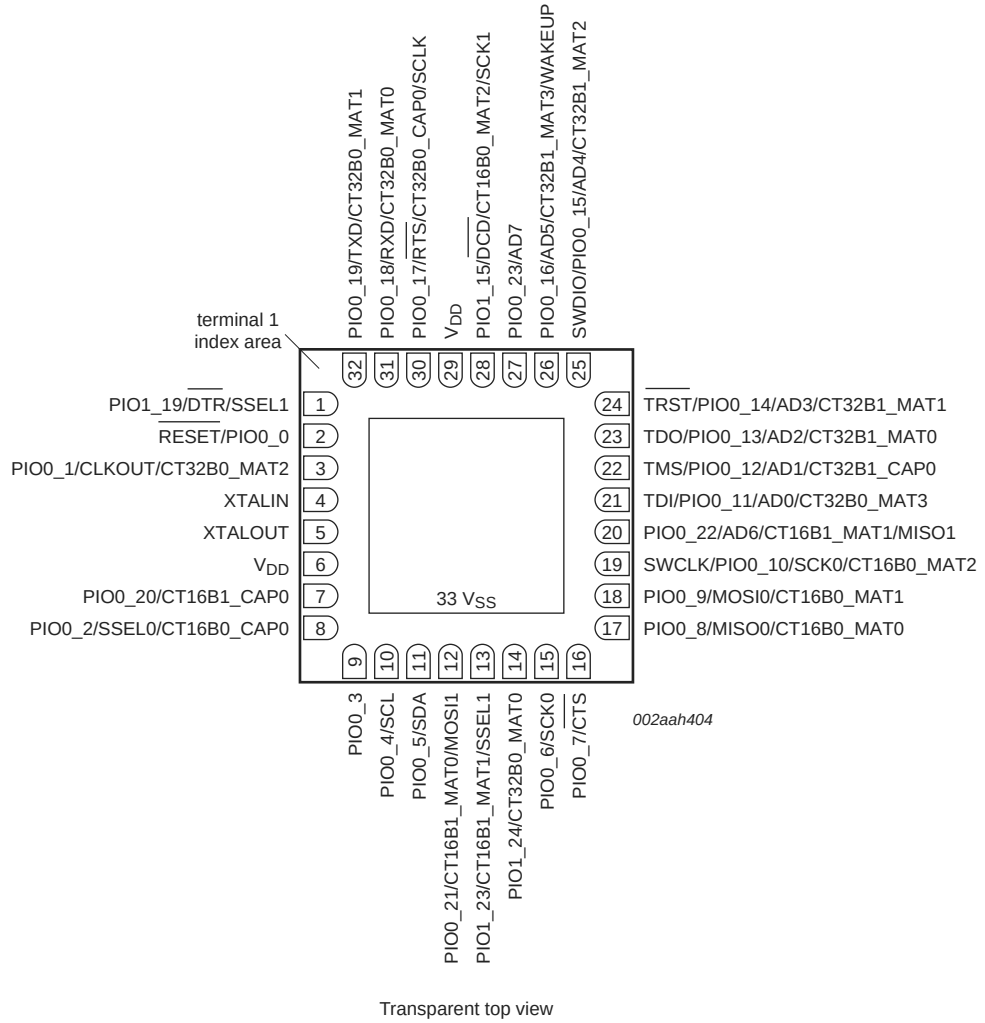
Type number	Flash in kB	EEPROM in kB	SRAM0 in kB	SRAM2 in kB	SRAM1 in kB[1]	Total SRAM in kB	I/O Handler	USART	I²C-bus FM+	SSP	ADC channels	GPIO pins
LPC11E35FHI33/501	64	4	8	2	2[1]	12	no	1	1	2	8	26
LPC11E36FBD64/501	96	4	8	2	2[1]	12	no	1	1	2	8	54
LPC11E36FHN33/501	96	4	8	2	2[1]	12	no	1	1	2	8	28
LPC11E37FBD48/501	128	4	8	2	2[1]	12	no	1	1	2	8	40
LPC11E37FBD64/501	128	4	8	2	2[1]	12	no	1	1	2	8	54
LPC11E37HFBD64/401	128	4	8	2	2[2]	10	yes	1	1	2	8	54

[1] For general-purpose use.

[2] For I/O Handler use only.

6. Pinning information

6.1 Pinning



Transparent top view

For parts LPC11E36FHN33/501

Fig 2. Pin configuration (HVQFN33, 7x7)

6.2 Pin description

Table 3 shows all pins and their assigned digital or analog functions in order of the GPIO port number. The default function after reset is listed first. All port pins have internal pull-up resistors enabled after reset except for the true open-drain pins PIO0_4 and PIO0_5.

Every port pin has a corresponding IOCON register for programming the digital or analog function, the pull-up/pull-down configuration, the repeater, and the open-drain modes.

The USART, counter/timer, and SSP functions are available on more than one port pin.

Table 3. Pin description

Symbol	Pin HVQFN33 (5x5)	Pin HVQFN33 (7x7)	Pin LQFP48	Pin LQFP64		Reset state [1]	Type	Description
$\overline{\text{RESET}}$/PIO0_0	2	2	3	4	[2]	I; PU	I	**$\overline{\text{RESET}}$ —** External reset input with 20 ns glitch filter. A LOW-going pulse as short as 50 ns on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. This pin also serves as the debug select input. LOW level selects the JTAG boundary scan. HIGH level selects the ARM SWD debug mode.
						-	I/O	**PIO0_0 —** General purpose digital input/output pin.
PIO0_1/CLKOUT/ CT32B0_MAT2	3	3	4	5	[3]	I; PU	I/O	**PIO0_1 —** General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler.
						-	O	**CLKOUT —** Clockout pin.
						-	O	**CT32B0_MAT2 —** Match output 2 for 32-bit timer 0.
PIO0_2/SSEL0/ CT16B0_CAP0/IOH_0	8	8	10	13	[3]	I; PU	I/O	**PIO0_2 —** General purpose digital input/output pin.
						-	I/O	**SSEL0 —** Slave select for SSP0.
						-	I	**CT16B0_CAP0 —** Capture input 0 for 16-bit timer 0.
						-	I/O	**IOH_0 —** I/O Handler input/output 0. LPC11E37HFBD64/401 only.
PIO0_3/R/IOH_1	9	9	14	19	[3]	I; PU	I/O	**PIO0_3 —** General purpose digital input/output pin.
						-	-	**R —** Reserved.
						-	I/O	**IOH_1 —** I/O Handler input/output 1. LPC11E37HFBD64/401 only.

Table 3. Pin description

Symbol	Pin HVQFN33 (5x5)	Pin HVQFN33 (7x7)	Pin LQFP48	Pin LQFP64		Reset state [1]	Type	Description
PIO0_4/SCL/IOH_2	10	10	15	20	[4]	I; IA	I/O	**PIO0_4 —** General purpose digital input/output pin (open-drain).
						-	I/O	**SCL —** I^2C-bus clock input/output (open-drain). High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
						-	I/O	**IOH_2 —** I/O Handler input/output 2. LPC11E37HFBD64/401 only.
PIO0_5/SDA/IOH_3	11	11	16	21	[4]	I; IA	I/O	**PIO0_5 —** General purpose digital input/output pin (open-drain).
						-	I/O	**SDA —** I^2C-bus data input/output (open-drain). High-current sink only if I^2C Fast-mode Plus is selected in the I/O configuration register.
						-	I/O	**IOH_3 —** I/O Handler input/output 3. LPC11E37HFBD64/401 only.
PIO0_6/R/ SCK0/IOH_4	15	15	22	29	[3]	I; PU	I/O	**PIO0_6 —** General purpose digital input/output pin.
						-	-	**R —** Reserved.
						-	I/O	**SCK0 —** Serial clock for SSP0.
						-	I/O	**IOH_4 —** I/O Handler input/output 4. LPC11E37HFBD64/401 only.
PIO0_7/$\overline{\text{CTS}}$/IOH_5	16	16	23	30	[5]	I; PU	I/O	**PIO0_7 —** General purpose digital input/output pin (high-current output driver).
						-	I	**$\overline{\text{CTS}}$ —** Clear To Send input for USART.
						-	I/O	**IOH_5 —** I/O Handler input/output 5. LPC11E37HFBD64/401 only.
PIO0_8/MISO0/ CT16B0_MAT0/R/IOH_6	17	17	27	36	[3]	I; PU	I/O	**PIO0_8 —** General purpose digital input/output pin.
						-	I/O	**MISO0 —** Master In Slave Out for SSP0.
						-	O	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.
						-	-	Reserved.
						-	I/O	**IOH_6 —** I/O Handler input/output 6. LPC11E37HFBD64/401 only.
PIO0_9/MOSI0/ CT16B0_MAT1/R/IOH_7	18	18	28	37	[3]	I; PU	I/O	**PIO0_9 —** General purpose digital input/output pin.
						-	I/O	**MOSI0 —** Master Out Slave In for SSP0.
						-	O	**CT16B0_MAT1 —** Match output 1 for 16-bit timer 0.
						-	-	Reserved.
						-	I/O	**IOH_7 —** I/O Handler input/output 7. LPC11E37HFBD64/401 only.

Table 3. Pin description

Symbol	Pin HVQFN33 (5x5)	Pin HVQFN33 (7x7)	Pin LQFP48	Pin LQFP64		Reset state [1]	Type	Description
PIO0_16/AD5/ CT32B1_MAT3/IOH_8/ WAKEUP	26	26	40	53	[6]	I; PU	I/O	**PIO0_16 —** General purpose digital input/output pin.
						-	I	**AD5 —** A/D converter, input 5.
						-	O	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
						-	I/O	**IOH_8 —** I/O Handler input/output 8. LPC11E37HFBD64/401 only.
						-	I	**WAKEUP —** Deep power-down mode wake-up pin with 20 ns glitch filter. Pull this pin HIGH externally before entering Deep power-down mode, then pull LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
PIO0_17/$\overline{\text{RTS}}$/ CT32B0_CAP0/SCLK	30	30	45	60	[3]	I; PU	I/O	**PIO0_17 —** General purpose digital input/output pin.
						-	O	**$\overline{\text{RTS}}$ —** Request To Send output for USART.
						-	I	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.
						-	I/O	**SCLK —** Serial clock input/output for USART in synchronous mode.
PIO0_18/RXD/ CT32B0_MAT0	31	31	46	61	[3]	I; PU	I/O	**PIO0_18 —** General purpose digital input/output pin.
						-	I	**RXD —** Receiver input for USART. Used in UART ISP mode.
						-	O	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO0_19/TXD/ CT32B0_MAT1	32	32	47	62	[3]	I; PU	I/O	**PIO0_19 —** General purpose digital input/output pin.
						-	O	**TXD —** Transmitter output for USART. Used in UART ISP mode.
						-	O	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO0_20/CT16B1_CAP0	7	7	9	11	[3]	I; PU	I/O	**PIO0_20 —** General purpose digital input/output pin.
						-	I	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO0_21/CT16B1_MAT0/ MOSI1	12	12	17	22	[3]	I; PU	I/O	**PIO0_21 —** General purpose digital input/output pin.
						-	O	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
						-	I/O	**MOSI1 —** Master Out Slave In for SSP1.

Table 3. Pin description

Symbol	Pin HVQFN33 (5x5)	Pin HVQFN33 (7x7)	Pin LQFP48	Pin LQFP64		Reset state [1]	Type	Description
XTALIN	4	4	6	8	[7]	-	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	5	5	7	9	[7]	-	-	Output from the oscillator amplifier.
V_{DD}	6; 29	6; 29	8; 44	10; 33; 48; 58		-	-	Supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
V_{SS}	33; 13; 14	33	5; 41	7; 54		-	-	Ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled; IA = inactive, no pull-up/down enabled; F = floating; If the pins are not used, tie floating pins to ground or power to minimize power consumption.

[2] 5 V tolerant pad. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See Figure 29 for the reset pad configuration.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 28).

[4] I^2C-bus pins compliant with the I^2C-bus specification for I^2C standard mode, I^2C Fast-mode, and I^2C Fast-mode Plus.

[5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 28); includes high-current output driver.

[6] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled and the pin is not 5 V tolerant (see Figure 28); includes digital input glitch filter.

[7] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). Leave XTALOUT floating.

7. Functional description

7.1 On-chip flash programming memory

The LPC11E3x contain up to 128 kB on-chip flash program memory. The flash can be programmed using In-System Programming (ISP) or In-Application Programming (IAP) via the on-chip boot loader software.

The flash memory is divided into 4 kB sectors with each sector consisting of 16 pages. Individual pages can be erased using the IAP erase page command.

7.2 EEPROM

The LPC11E3x contain 4 kB of on-chip byte-erasable and byte-programmable EEPROM data memory. The EEPROM can be programmed using In-Application Programming (IAP) via the on-chip boot loader software.

7.8.1 Features

- GPIO pins can be configured as input or output by software.
- All GPIO pins default to inputs with interrupt disabled at reset.
- Pin registers allow pins to be sensed and set individually.
- Up to eight GPIO pins can be selected from all GPIO pins to create an edge- or level-sensitive GPIO interrupt request.
- Any pin or pins in each port can trigger a port interrupt.

7.9 I/O Handler (LPC11E37HFBD64/401 only)

The I/O Handler is a software library-supported hardware engine for emulating serial interfaces and DMA. The I/O Handler can emulate serial interfaces such as UART, I^2C, or I^2S with no or very low additional CPU load. The software libraries are available with supporting application notes from NXP (see http://www.LPCware.com.) LPCXpresso, Keil, and IAR IDEs are supported. I/O Handler library code must be executed from the memory area 0x2000 0000 to 0x2000 07FF. This memory is not available for other use.

For application examples, see Section 11.7 “I/O Handler software library applications”.

7.10 USART

The LPC11E3x contains one USART.

The USART includes full modem control, support for synchronous mode, and a smart card interface. The RS-485/9-bit mode allows both software address detection and automatic address detection using 9-bit mode.

The USART uses a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

7.10.1 Features

- Maximum USART data bit rate of 3.125 Mbit/s.
- 16 byte receive and transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- Fractional divider for baud rate control, auto baud capabilities and FIFO control mechanism that enables software flow control implementation.
- Support for RS-485/9-bit mode.
- Support for modem control.
- Support for synchronous mode.
- Includes smart card interface.

7.11 SSP serial I/O controller

The SSP controllers operate on a SSP, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. The SSP supports full duplex transfers, with frames of 4 bit to 16 bit of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.11.1 Features

- Maximum SSP speed of 25 Mbit/s (master) or 4.17 Mbit/s (slave) (in SSP mode).
- Compatible with Motorola SPI (Serial Peripheral Interface), 4-wire Texas Instruments SSI (Serial Synchronous Interface), and National Semiconductor Microwire buses.
- Synchronous serial communication.
- Master or slave operation.
- 8-frame FIFOs for both transmit and receive.
- 4-bit to 16-bit frame.

7.12 I^2C-bus serial I/O controller

The LPC11E3x contain one I^2C-bus controller.

The I^2C-bus is bidirectional for inter-IC control using only two wires: a Serial CLock line (SCL) and a Serial DAta line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I^2C-bus is a multi-master bus, and more than one bus master connected to the interface can be controlled the bus.

7.12.1 Features

- The I^2C-interface is an I^2C-bus compliant interface with open-drain pins. The I^2C-bus interface supports Fast-mode Plus with bit rates up to 1 Mbit/s.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I^2C-bus can be used for test and diagnostic purposes.
- The I^2C-bus controller supports multiple address recognition and a bus monitor mode.

7.17.1.3 Watchdog oscillator

The watchdog oscillator can be used as a clock source that directly drives the CPU, the watchdog timer, or the CLKOUT pin. The watchdog oscillator nominal frequency is programmable between 9.4 kHz and 2.3 MHz. The frequency spread over processing and temperature is ±40 % (see also Table 13).

7.17.2 System PLL

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32. The CCO operates in the range of 156 MHz to 320 MHz. To support this frequency range, an additional divider keeps the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider can be set to divide by 2, 4, 8, or 16 to produce the output clock. The PLL output frequency must be lower than 100 MHz. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset. Software can enable the PLL later. The program must configure and activate the PLL, wait for the PLL to lock, and then connect to the PLL as a clock source. The PLL settling time is 100 μs.

7.17.3 Clock output

The LPC11E3x feature a clock output function that routes the IRC oscillator, the system oscillator, the watchdog oscillator, or the main clock to an output pin.

7.17.4 Wake-up process

The LPC11E3x begin operation by using the 12 MHz IRC oscillator as the clock source at power-up and when awakened from Deep power-down mode. This mechanism allows chip operation to resume quickly. If the application uses the main oscillator or the PLL, software must enable these components and wait for them to stabilize. Only then can the system use the PLL and main oscillator as a clock source.

7.17.5 Power control

The LPC11E3x support various power control features. There are four special modes of processor power reduction: Sleep mode, Deep-sleep mode, Power-down mode, and Deep power-down mode. The CPU clock rate can also be controlled as needed by changing clock sources, reconfiguring PLL values, and/or altering the CPU clock divider value. This power control mechanism allows a trade-off of power versus processing speed based on application requirements. In addition, a register is provided for shutting down the clocks to individual on-chip peripherals. This register allows fine-tuning of power consumption by eliminating all dynamic power use in any peripherals that are not required for the application. Selected peripherals have their own clock divider which provides even better power control.

7.17.5.1 Power profiles

The power consumption in Active and Sleep modes can be optimized for the application through simple calls to the power profile. The power configuration routine configures the LPC11E3x for one of the following power modes:

- Default mode corresponding to power configuration after reset.
- CPU performance mode corresponding to optimized processing capability.

7.18 Emulation and debugging

Debug functions are integrated into the ARM Cortex-M0. Serial wire debug functions are supported in addition to a standard JTAG boundary scan. The ARM Cortex-M0 is configured to support up to four breakpoints and two watch points.

The $\overline{\text{RESET}}$ pin selects between the JTAG boundary scan ($\overline{\text{RESET}}$ = LOW) and the ARM SWD debug ($\overline{\text{RESET}}$ = HIGH). The ARM SWD debug port is disabled while the LPC11E3x is in reset.

To perform boundary scan testing, follow these steps:

1. Erase any user code residing in flash.
2. Power up the part with the $\overline{\text{RESET}}$ pin pulled HIGH externally.
3. Wait for at least 250 μs.
4. Pull the $\overline{\text{RESET}}$ pin LOW externally.
5. Perform boundary scan operations.
6. Once the boundary scan operations are completed, assert the $\overline{\text{TRST}}$ pin to enable the SWD debug mode, and release the $\overline{\text{RESET}}$ pin (pull HIGH).

Remark: The JTAG interface cannot be used for debug purposes.

Table 6. ADC static characteristics

T_{amb} = −40 °C to +85 °C unless otherwise specified; ADC frequency 4.5 MHz, V_{DD} = 2.5 V to 3.6 V.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IA}	analog input voltage			0	-	V_{DD}	V
C_{ia}	analog input capacitance			-	-	1	pF
E_D	differential linearity error		[1][2]	-	-	±1	LSB
$E_{L(adj)}$	integral non-linearity		[3]	-	-	±1.5	LSB
E_O	offset error		[4]	-	-	±3.5	LSB
E_G	gain error		[5]	-	-	0.6	%
E_T	absolute error		[6]	-	-	±4	LSB
R_{vsi}	voltage source interface resistance			-	-	40	kΩ
R_i	input resistance		[7][8]	-	-	2.5	MΩ

[1] The ADC is monotonic, there are no missing codes.

[2] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 8.

[3] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 8.

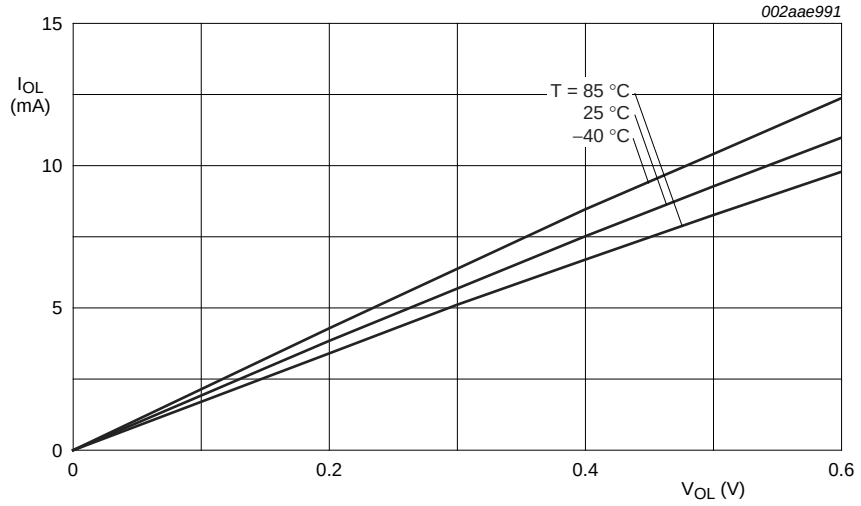
[4] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 8.

[5] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 8.

[6] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See Figure 8.

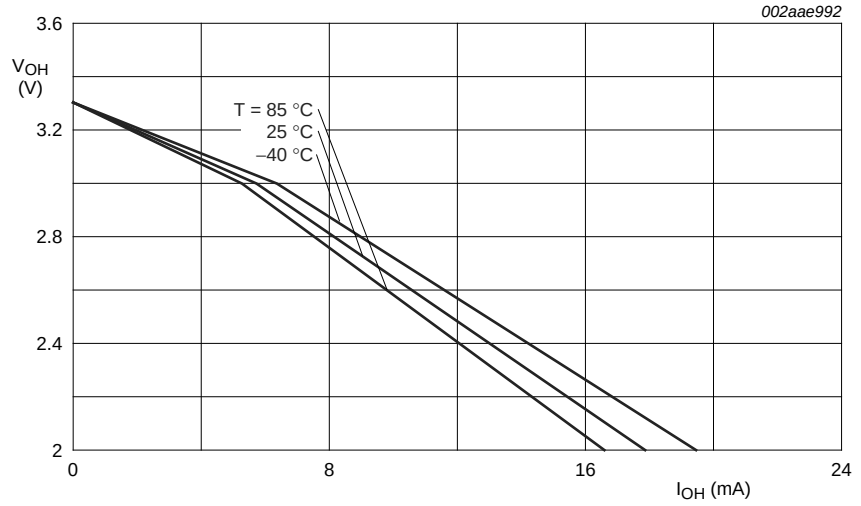
[7] T_{amb} = 25 °C; maximum sampling frequency f_s = 400 kSamples/s and analog input capacitance C_{ia} = 1 pF.

[8] Input resistance R_i depends on the sampling frequency fs: $R_i = 1 / (f_s \times C_{ia})$.



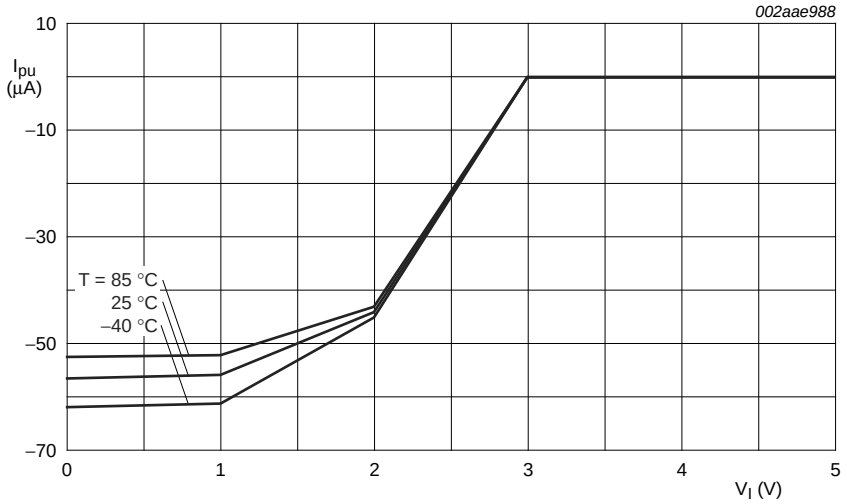
Conditions: V_{DD} = 3.3 V; standard port pins and PIO0_7.

Fig 17. Typical LOW-level output current I_{OL} versus LOW-level output voltage V_{OL}



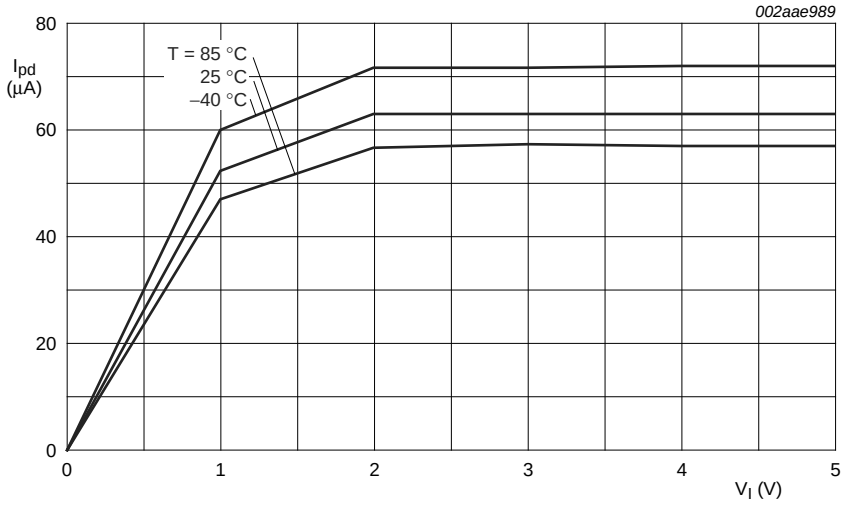
Conditions: V_{DD} = 3.3 V; standard port pins.

Fig 18. Typical HIGH-level output voltage V_{OH} versus HIGH-level output source current I_{OH}



Conditions: V_{DD} = 3.3 V; standard port pins.

Fig 19. Typical pull-up current I_{pu} versus input voltage V_I



Conditions: V_{DD} = 3.3 V; standard port pins.

Fig 20. Typical pull-down current I_{pd} versus input voltage V_I

10. Dynamic characteristics

10.1 Flash memory

Table 9. Flash characteristics

T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
N_{endu}	endurance		[1]	10000	100000	-	cycles
t_{ret}	retention time	powered		10	-	-	years
		unpowered		20	-	-	years
t_{er}	erase time	sector or multiple consecutive sectors		95	100	105	ms
t_{prog}	programming time		[2]	0.95	1	1.05	ms

[1] Number of program/erase cycles.

[2] Programming times are given for writing 256 bytes from RAM to the flash. Data must be written to the flash in blocks of 256 bytes.

Table 10. EEPROM characteristics

T_{amb} = −40 °C to +85 °C; V_{DD} = 2.7 V to 3.6 V. Based on JEDEC NVM qualification. Failure rate < 10 ppm for parts as specified below.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
N_{endu}	endurance		100000	1000000	-	cycles
t_{ret}	retention time	powered	100	200	-	years
		unpowered	150	300	-	years
t_{prog}	programming time	64 bytes	-	2.9	-	ms

10.2 External clock

Table 11. Dynamic characteristic: external clock

T_{amb} = −40 °C to +85 °C; V_{DD} over specified ranges.[1]

Symbol	Parameter	Min	Typ[2]	Max	Unit
f_{osc}	oscillator frequency	1	-	25	MHz
$T_{cy(clk)}$	clock cycle time	40	-	1000	ns
t_{CHCX}	clock HIGH time	$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCX}	clock LOW time	$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCH}	clock rise time	-	-	5	ns
t_{CHCL}	clock fall time	-	-	5	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

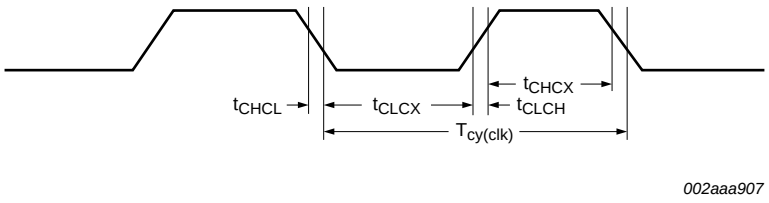


Fig 21. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

10.3 Internal oscillators

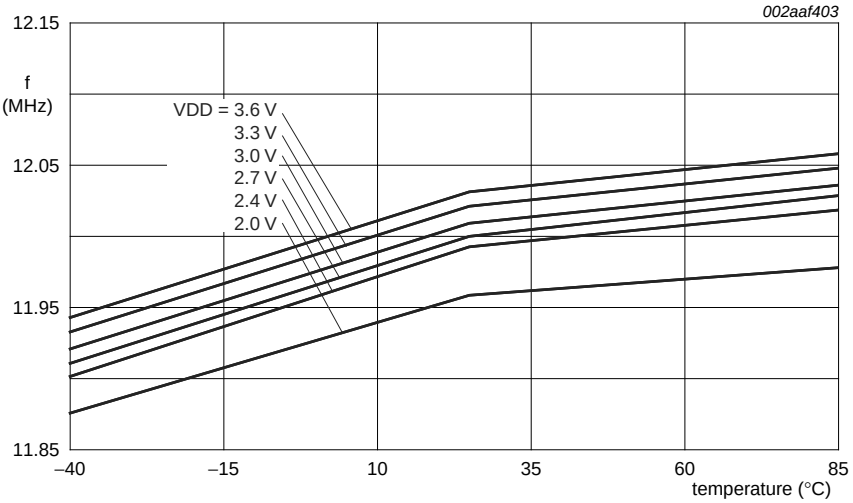
Table 12. Dynamic characteristics: IRC

T_{amb} = −40 °C to +85 °C; 2.7 V ≤ V_{DD} ≤ 3.6 V[1].

Symbol	Parameter	Conditions		Min	Typ[2]	Max	Unit
$f_{osc(RC)}$	internal RC oscillator frequency	-		11.88	12	12.12	MHz

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.



Conditions: Frequency values are typical values. 12 MHz ± 1 % accuracy is guaranteed for 2.7 V ≤ V_{DD} ≤ 3.6 V and T_{amb} = −40 °C to +85 °C. Variations between parts may cause the IRC to fall outside the 12 MHz ± 1 % accuracy specification for voltages below 2.7 V.

Fig 22. Internal RC oscillator frequency versus temperature

10.6 SSP interface

Table 16. Dynamic characteristics of SPI pins in SPI mode

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
SPI master (in SPI mode)							
$T_{cy(clk)}$	clock cycle time	full-duplex mode	[1]	50	-	-	ns
		when only transmitting	[1]	40			ns
t_{DS}	data set-up time	in SPI mode $2.4\ V \leq V_{DD} \leq 3.6\ V$	[2]	15	-	-	ns
		$2.0\ V \leq V_{DD} < 2.4\ V$	[2]	20			ns
		$1.8\ V \leq V_{DD} < 2.0\ V$	[2]	24	-	-	ns
t_{DH}	data hold time	in SPI mode	[2]	0	-	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode	[2]	-	-	10	ns
$t_{h(Q)}$	data output hold time	in SPI mode	[2]	0	-	-	ns
SPI slave (in SPI mode)							
$T_{cy(PCLK)}$	PCLK cycle time			20	-	-	ns
t_{DS}	data set-up time	in SPI mode	[3][4]	0	-	-	ns
t_{DH}	data hold time	in SPI mode	[3][4]	$3 \times T_{cy(PCLK)} + 4$	-	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode	[3][4]	-	-	$3 \times T_{cy(PCLK)} + 11$	ns
$t_{h(Q)}$	data output hold time	in SPI mode	[3][4]	-	-	$2 \times T_{cy(PCLK)} + 5$	ns

[1] $T_{cy(clk)} = (SSPCLKDIV \times (1 + SCR) \times CPSDVSR) / f_{main}$. The clock cycle time derived from the SPI bit rate $T_{cy(clk)}$ is a function of the main clock frequency f_{main}, the SPI peripheral clock divider (SSPCLKDIV), the SPI SCR parameter (specified in the SSP0CR0 register), and the SPI CPSDVSR parameter (specified in the SPI clock prescale register).

[2] $T_{amb} = -40\ °C$ to $85\ °C$.

[3] $T_{cy(clk)} = 12 \times T_{cy(PCLK)}$.

[4] $T_{amb} = 25\ °C$; for normal voltage supply range: $V_{DD} = 3.3\ V$.

11.7.3 I/O Handler I²C

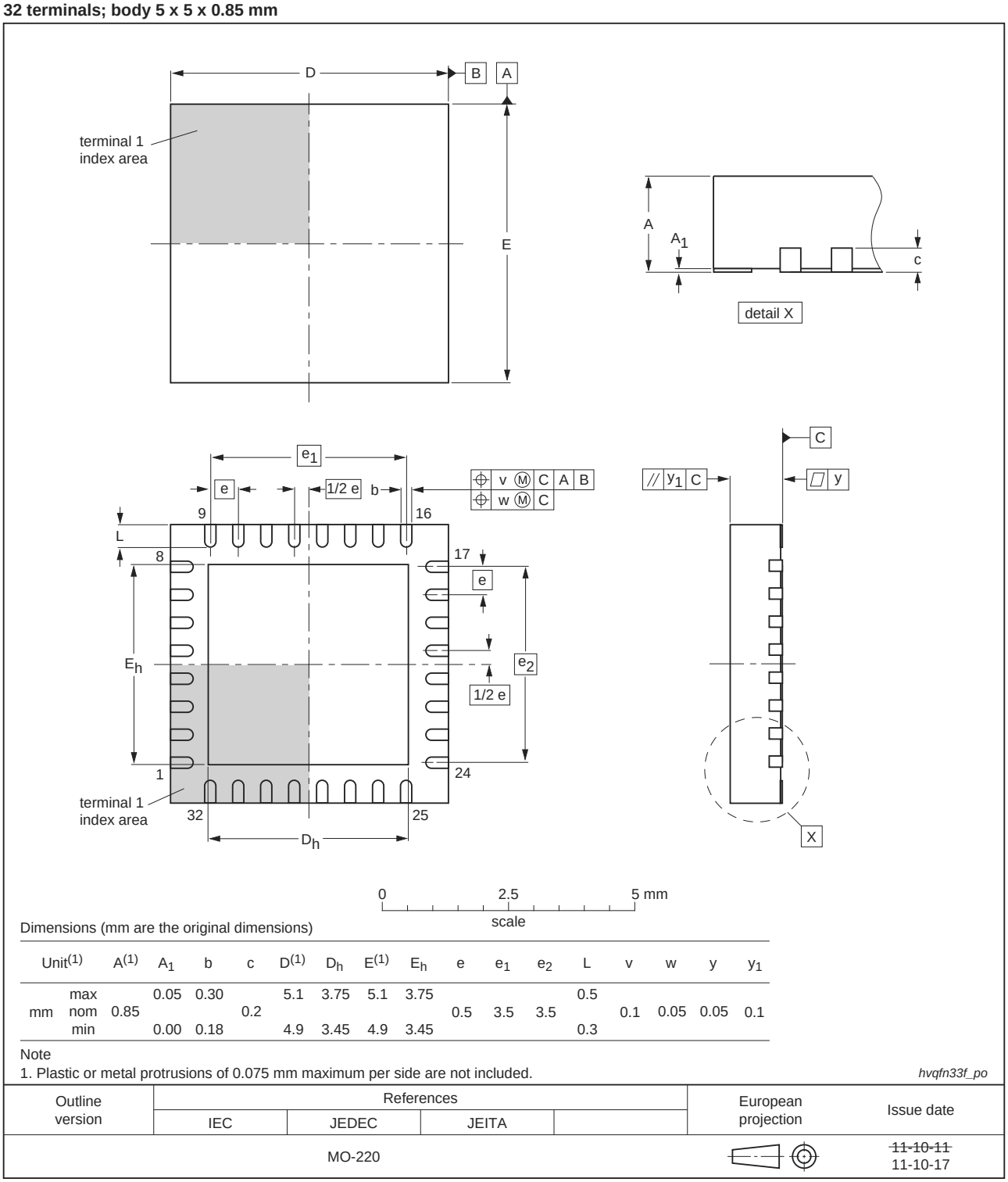
The I/O Handler I²C library allows to have an additional I²C-bus master. I²C read, I²C write and combined I²C read/write are supported. Data is automatically read from and written to user-defined buffers.

The I/O Handler I²C library combined with the on-chip I²C module allows to have two distinct I²C buses, allowing to separate low-speed from high-speed devices or bridging two I²C buses.

11.7.4 I/O Handler DMA

The I/O Handler DMA library offers DMA-like functionality. Four types of transfer are supported: memory to memory, memory to peripheral, peripheral to memory and peripheral to peripheral. Supported peripherals are USART, SSP0/1, ADC and GPIO. DMA transfers can be triggered by the source/target peripheral, software, counter/timer module CT16B1, or I/O Handler pin PIO1_6/IOH_16.

HVQFN33: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm



Dimensions (mm are the original dimensions)

Unit[1]		A[1]	A_1	b	c	D[1]	D_h	E[1]	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	max	0.85	0.05	0.30	0.2	5.1	3.75	5.1	3.75	0.5	3.5	3.5	0.5	0.1	0.05	0.05	0.1
	nom																
	min		0.00	0.18		4.9	3.45	4.9	3.45				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

hvqfn33f_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
		MO-220				~~11-10-11~~ 11-10-17

Fig 32. Package outline HVQFN33 (5 x 5 x 0.85 mm)

14. Revision history

Table 19. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC11E3X v.2.3	20140911	Product data sheet		LPC11E3X v.2.2
Modifications:	Added part LPC11E35FHI33/501.			
LPC11E3X v.2.2	20140114	Product data sheet	-	LPC11E3X v.2.1
Modifications:	ISP mode removed from pin PIO0_3 in Table 3.			
LPC11E3X v.2.1	20131230	Product data sheet	-	LPC11E3X v.2
Modifications:	Add reserved function to pins PIO0_8/MISO0/CT16B0_MAT0/R/IOH_6 and PIO0_9/MOSI0/CT16B0_MAT1/R/IOH_7.			
LPC11E3X v.2	20131121	Product data sheet	-	LPC11E3X v.1.1
Modifications:	• Parts LPC11E3HFBD64/401 added. • 8 kB SRAM block at 0x1000 000 renamed to SRAM0 in Figure 5. • I/O Handler pins added in Table 3. • Typical range of watchdog oscillator frequency changed to 9.4 kHz to 2.3 MHz. • Section 11.7 “I/O Handler software library applications” added. • Condition V_{DD} = 0 V added to Parameter V_I in Table 5 for clarity.			
LPC11E3X v.1.1	20130924	Product data sheet	-	LPC11E3X v.1
Modifications:	• Table 3: Added “5 V tolerant pad” to $\overline{\text{RESET}}$/PIO0_0 table note. • Table 7: Removed BOD interrupt level 0. • Added Section 11.5 “ADC effective input impedance”. • Programmable glitch filter is enabled by default. See Section 7.7.1. • Table 5 “Static characteristics” added Pin capacitance section. • Table 4 “Limiting values”: – Updated V_{DD} min and max. – Updated V_I conditions. • Table 10 “EEPROM characteristics”: – Removed f_{clk} and t_{er}; the user does not have control over these parameters. – Changed the t_{prog} from 1.1 ms to 2.9 ms; the EEPROM IAP always does an erase and program, thus the total program time is $t_{er} + t_{prog}$.			
LPC11E3X v.1	20121107	Objective data sheet	-	-

17. Contents

continued >>